

## Material Set Change:

Package Material Set		Carsem	ASE Chungli
16L SOICN	Die Attach	Ablestik 84-1 LMISR4	Hitachi EN4900
	Mold Compound	Sumitomo 6600H	Hitachi CEL9240HF10AK Sumitomo G700
	Wire	0.8mil, 1.0mil and 1.2/1.3 mil Gold wire	0.8mil, 1mil and 1.2/1.3mil Gold Wire

### Reliability Qualification Results of 16L SOICn package at ASE Chungli (AET)

QUALIFICATION RESULTS			
Test	Conditions	Sample Size	RESULT
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	<b>PASS</b>
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	<b>PASS</b>
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	<b>PASS</b>
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	<b>PASS</b>
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	<b>PASS</b>
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	<b>PASS ±500V</b>

\*Preconditioned per JEDEC/IPC J-STD-020